

HSF

NOTES:

Current Rating:5.0A AMP
 Contact Resistance:10milliohm Max
 Withstand Voltage:1000V AC/Minute
 Insulation Resistance:1000Megohm Min
 Operation Temperature:-40°C to +105°C

Housing Material:LCP+30%GF(UL94V-0)
 Contact Material:Copper alloy
 Contact plating:Au/Sn over Ni Plating

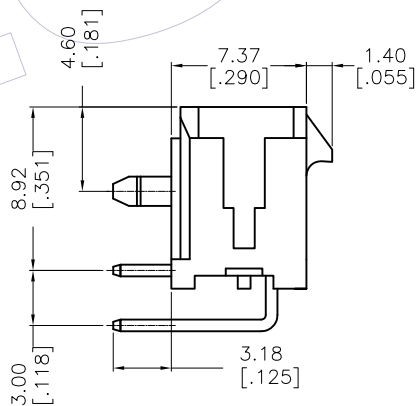
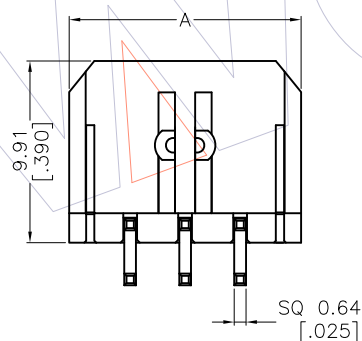
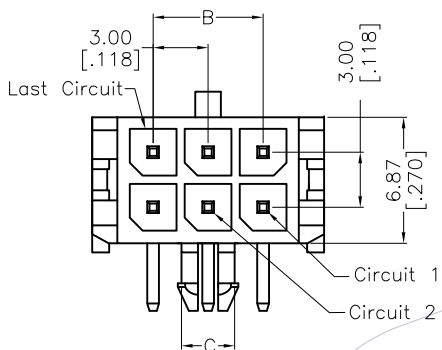
Ordering Information

WF3001-2 WR XX B X 1

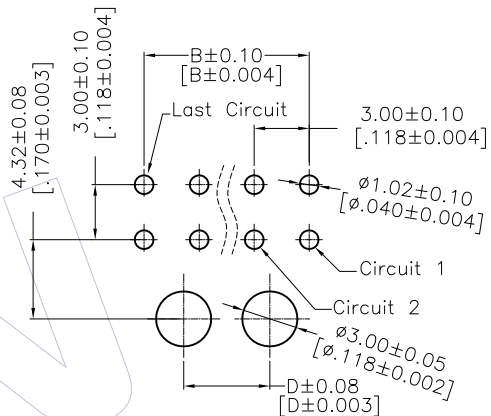
Terminal shape:
WR:Wafer 90° DIP

NO.of Pins Per
Row:01~12Pin

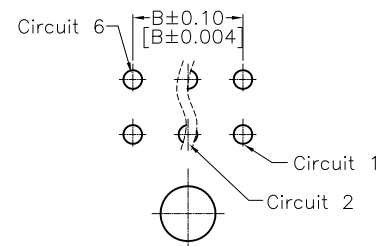
Packing:
0=PE Bag
T=Tube
A=Tray
R=Tape&Reel



RECOMMENDED PCB LAYOUT TOLERANCE IS ±0.05



6-24 Circuit PCB LAYOUT



2-6 Circuit PCB LAYOUT

Circuit	A	B	C	D
02	6.65[0.262]	NA	2.90[0.114]	NA
04	9.65[0.380]	3.00[0.118]	2.90[0.114]	NA
06	12.65[0.498]	6.00[0.236]	2.90[0.114]	NA
08	15.65[0.616]	9.00[0.355]	7.60[0.299]	4.70[0.185]
10	18.65[0.735]	12.00[0.473]	10.60[0.418]	7.70[0.303]
12	21.65[0.853]	15.00[0.591]	13.60[0.536]	10.70[0.421]
14	24.65[0.971]	18.00[0.709]	16.60[0.654]	13.70[0.539]
16	27.65[1.089]	21.00[0.827]	19.60[0.772]	16.70[0.657]
18	30.65[1.207]	24.00[0.945]	22.60[0.890]	19.70[0.776]
20	33.65[1.325]	27.00[1.063]	25.60[1.008]	22.70[0.894]
22	36.65[1.443]	30.00[1.181]	28.60[1.126]	25.70[1.012]
24	39.65[1.561]	33.00[1.299]	31.60[1.244]	28.70[1.130]

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION		DRAW FZY	DATE	SCALE	1:1	PART NO.
				X.X	±0.40					
A1	2012.05.03	料号由WF3001-2WRHXXBX1变更为WF3001-2WRXXBX1	Atomy	X.XX	±0.25	CHECK	DATE	UNIT	mm inch	TITLE: 3.00 WAFER DUAL ROW 90° DIP WITH POST
A0	2011.12.20	NEW	-	X.XXX	±0.15	APPROVE	DATE	SIZE	A4	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle	± 3'		DATE	SHEET	1/1	
				DIM	TOL			PROJ.		